

Title (en)  
MATERIAL FOR INSULATING SUBSTRATE, PRINTED BOARD, LAMINATE, COPPER FOIL WITH RESIN, COPPER-CLAD LAMINATE, POLYIMIDE FILM, FILM FOR TAB, AND PREPREG

Title (de)  
MATERIAL FÜR ISOLIERENDES SUBSTRAT, LEITERPLATTE, LAMINAT, KUPFERFOLIE MIT HARZ, KUPFERUMMANTELTES LAMINAT, POLYIMIDFOLIE, FOLIE FÜR TABS UND PREPREGS

Title (fr)  
MATERIAU DE SUBSTRATS ISOLANTS, STRATIFIE POUR CARTE A CIRCUIT IMPRIME, FEUILLE DE CUIVRE AVEC RESINE, STRATIFIE A REVETEMENT DE CUIVRE, FILM POLYIMIDE, FILM POUR TAB, ET PREIMPREGNE

Publication  
**EP 1350815 A4 20080430 (EN)**

Application  
**EP 01999262 A 20011210**

Priority  

- JP 0110771 W 20011210
- JP 2000374799 A 20001208
- JP 2001096652 A 20010329
- JP 2001141887 A 20010511
- JP 2001141888 A 20010511

Abstract (en)  
[origin: EP1350815A1] It is an object of the invention to provide a material for insulating substrate, a printed board, a laminate, copper foil with resin, a copper-clad laminate, a polyimide film, a film for TAB and a prepreg, which are excellent in physical properties, dimensional stability, heat resistance, flame retardancy etc. and exhibit an excellent flame retardant effect particularly by a shape retention effect at the time of combustion <??>The invention provides a material for insulating substrate, comprising 100 parts by weight of a thermoplastic resin or a mixture of a thermoplastic resin and a thermosetting resin and 0.1 to 100 parts by weight of a layered silicate.

IPC 1-7  
**C08L 101/00**; **C08K 3/34**; **C08J 5/00**; **B32B 27/20**; **H01L 23/14**; **H01B 3/00**; **H05K 1/03**; **H05K 3/46**

IPC 8 full level  
**B32B 15/08** (2006.01); **C08K 3/34** (2006.01); **C08K 7/00** (2006.01); **H01B 3/30** (2006.01); **H01L 23/14** (2006.01); **H05K 1/03** (2006.01)

CPC (source: EP KR US)  
**B32B 15/08** (2013.01 - EP US); **C08K 3/34** (2013.01 - EP US); **C08K 7/00** (2013.01 - EP US); **H01B 3/30** (2013.01 - EP US); **H01L 23/145** (2013.01 - EP US); **H05K 1/03** (2013.01 - KR); **H05K 1/0373** (2013.01 - EP US); **H01L 2924/0002** (2013.01 - EP US); **H05K 2201/0129** (2013.01 - EP US); **H05K 2201/0154** (2013.01 - EP US); **Y10T 428/265** (2015.01 - EP US); **Y10T 428/31518** (2015.04 - EP US); **Y10T 428/31522** (2015.04 - EP US); **Y10T 428/31678** (2015.04 - EP US); **Y10T 428/31681** (2015.04 - EP US)

C-Set (source: EP US)  
**H01L 2924/0002 + H01L 2924/00**

Citation (search report)  

- [E] EP 1245632 A1 20021002 - SEKISUI CHEMICAL CO LTD [JP]
- [X] EP 0771854 A2 19970507 - MITSUBISHI CHEM CORP [JP]
- [X] EP 0995591 A1 20000426 - SHOWA DENKO KK [JP]
- See references of WO 0246312A1

Cited by  
EP1473329A4; EP2219211A1; US7682691B2; US8568867B2; US9161440B2; US7928154B2; WO2008002890A3; WO2008002889A3; WO2008002867A3; WO2008002880A3; US7915332B2; US7928155B2; TWI498367B

Designated contracting state (EPC)  
DE FR GB

DOCDB simple family (publication)  
**EP 1350815 A1 20031008**; **EP 1350815 A4 20080430**; AU 2109702 A 20020618; CA 2429683 A1 20020613; CN 1254512 C 20060503; CN 1479768 A 20040303; KR 100851799 B1 20080813; KR 20030064804 A 20030802; TW 559835 B 20031101; US 2004053061 A1 20040318; US 2008268237 A1 20081030; US 2008268257 A1 20081030; WO 0246312 A1 20020613

DOCDB simple family (application)  
**EP 01999262 A 20011210**; AU 2109702 A 20011210; CA 2429683 A 20011210; CN 01820176 A 20011210; JP 0110771 W 20011210; KR 20037007638 A 20030607; TW 90130488 A 20011210; US 16490608 A 20080630; US 16495208 A 20080630; US 43395603 A 20031024